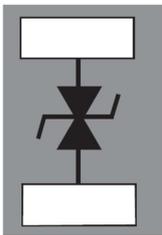


Low clamping and low capacitance bidirectional single line ESD protection



0201 package



Features

- Low clamping voltage $V_{CL} = 18\text{ V}$
- Bidirectional device
- Low leakage current
- 0201 package
- Ultra-low PCB area: 0.18 mm^2
- ECOPACK2 compliant
- Exceeds IEC 61000-4-2 level 4 standard:
 - $\pm 25\text{ kV}$ (contact discharge)
 - $\pm 30\text{ kV}$ (air discharge)

Application

Where transient over voltage protection in ESD sensitive equipment is required, such as:

- Smartphones, mobile phones and accessories
- Tablets and notebooks
- Portable multimedia devices and accessories
- Wearable, home automation, healthcare
- Highly integrated systems

Product status link

[ESDALC14-1BF4](#)

Product summary

Order code	ESDALC14-1BF4
Package	ST0201
Packing	Tape and reel

Description

The **ESDALC14-1BF4** is a bidirectional single line TVS diode designed to protect the data line or other I/O ports against ESD transients.

The device is ideal for applications where both reduced line capacitance and board space saving are required.

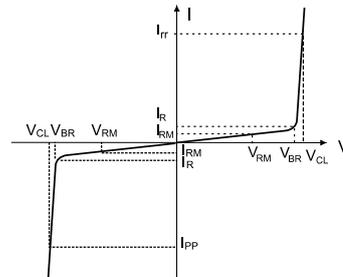
1 Characteristics

Table 1. Absolute maximum ratings ($T_{amb} = 25\text{ °C}$)

Symbol	Parameter		Value	Unit
V_{PP}	Peak pulse voltage	IEC 61000-4-2 contact discharge	25	kV
		IEC 61000-4-2 air discharge	30	
P_{PP}	Peak pulse power dissipation (8/20 μ s)		100	W
I_{PP}	Peak pulse current (8/20 μ s)		5	A
T_j	Maximum operating junction temperature range		-40 to +150	$^{\circ}$ C
T_{stg}	Storage temperature range		-65 to +150	$^{\circ}$ C
T_L	Maximum lead temperature for soldering during 10 s		260	$^{\circ}$ C

Figure 1. Electrical characteristics (definitions)

Symbol	Parameter
V_{BR}	= Breakdown voltage
V_{RM}	= Stand-of voltage
V_{CL}	= Clamping voltage
I_{RM}	= Leakage current at V_{RM}
I_{PP}	= Peak pulse current
R_d	= Dynamic impedance
C_{LINE}	= Input capacitance per line


Table 2. Electrical characteristics ($T_{amb} = 25\text{ °C}$)

Symbol	Test condition	Min.	Typ.	Max.	Unit
V_{BR}	$I_R = 1\text{ mA}$	13			V
I_{RM}	$V_{RM} = 12\text{ V}$			100	nA
V_{CL}	8 kV contact discharge after 30 ns, IEC 61000-4-2		18		V
C_{LINE}	$F = 1\text{ MHz}$, $V_{LINE} = 0\text{ V}$, $V_{OSC} = 30\text{ mV}$		22	25	pF

1.1 Characteristics (curves)

Figure 2. Leakage current versus junction temperature (typical values)

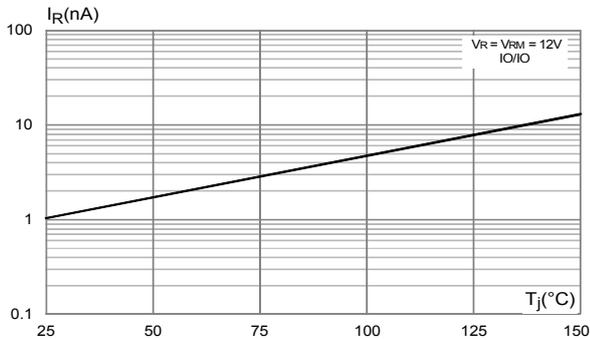


Figure 3. Junction capacitance versus applied voltage (typical values)

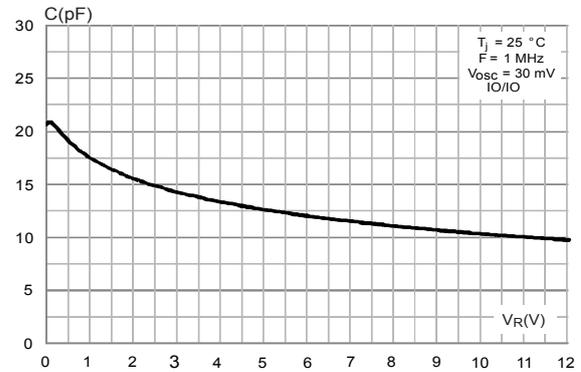


Figure 4. ESD response to IEC 61000-4-2 (+8 kV contact discharge)

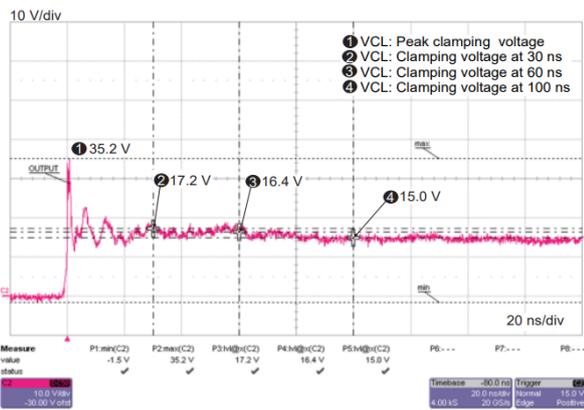


Figure 5. ESD response to IEC 61000-4-2 (-8 kV contact discharge)

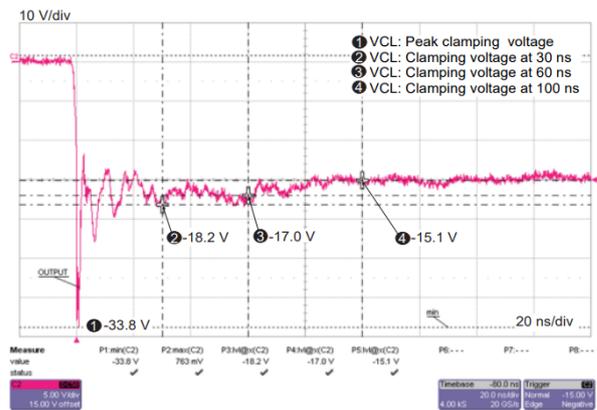


Figure 6. Positive TLP characteristic

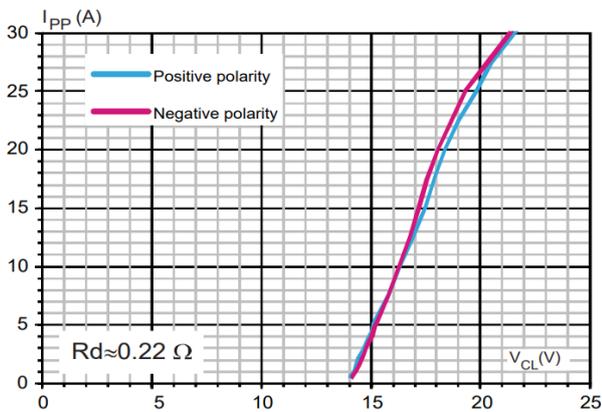
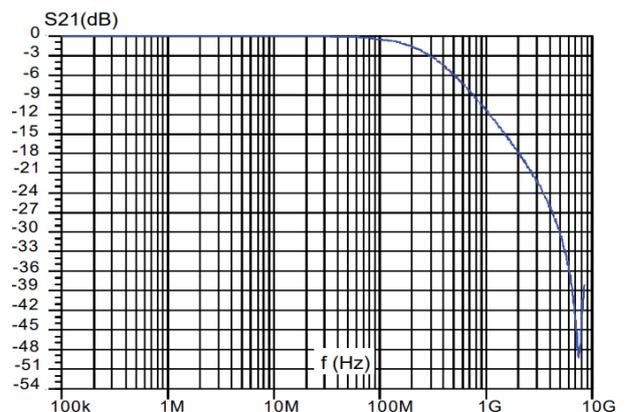


Figure 7. S21 attenuation measurement result

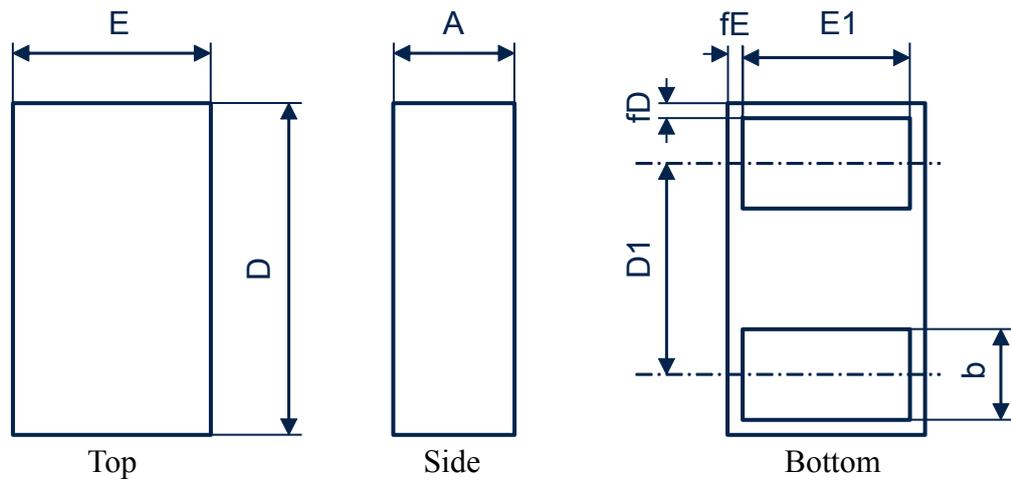


2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

2.1 ST0201 package information

Figure 8. Package outline



Note: The marking codes can be rotated by 90 ° or 180° to differentiate assembly location. In no case should this product marking be used to orient the component for its placement on a PCB. Only pin 1 mark is to be used for this purpose.

Table 3. Package mechanical data

Ref.	Dimensions		
	Millimeters		
	Min.	Typ.	Max.
A	0.280	0.300	0.320
b	0.125	0.140	0.155
D	0.570	0.600	0.630
D1		0.350	
E	0.270	0.300	0.330
E1	0.175	0.190	0.255
fD	0.110	0.125	0.140
fE	0.040	0.055	0.070

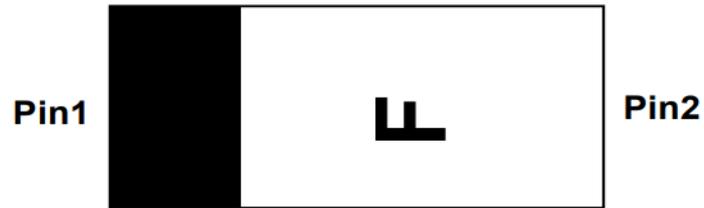
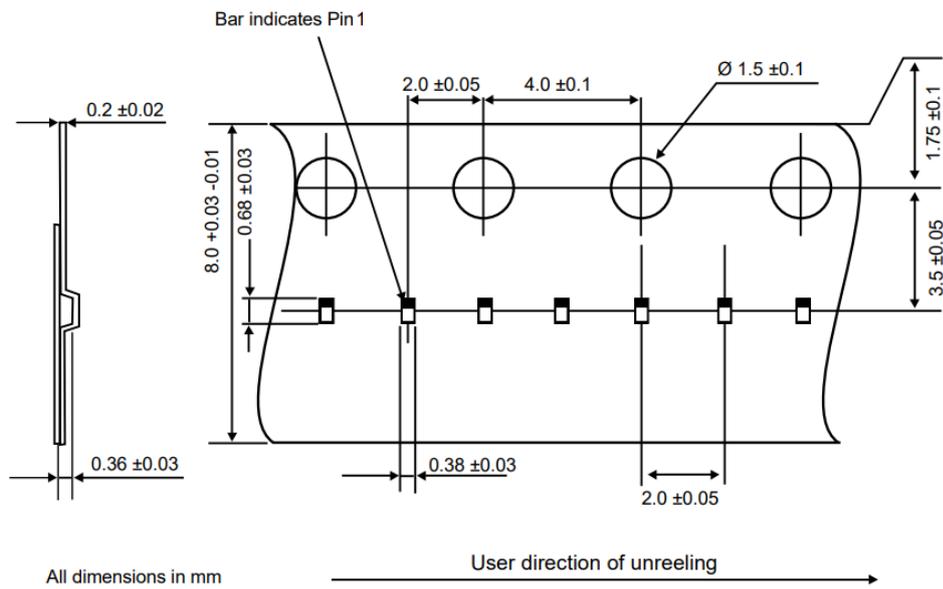


Figure 9. Tape and reel specification (in mm)

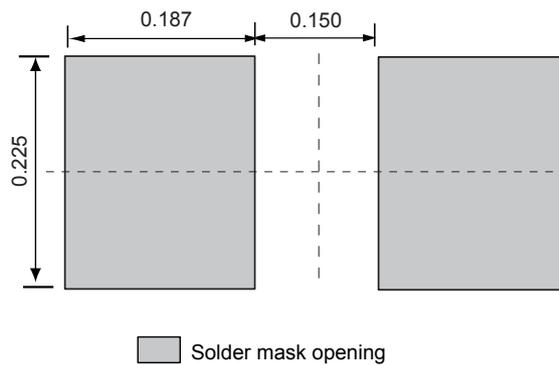


3 Recommendation on PCB assembly

3.1 Footprint

1. Footprint in mm
 - a. SMD footprint design is recommended.

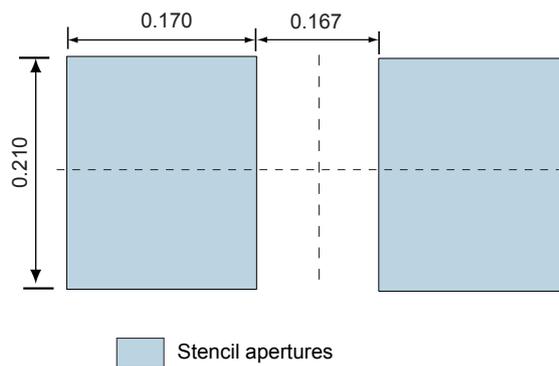
Figure 10. Footprint in mm



3.2 Stencil opening design

1. Reference design
 - a. Stencil opening thickness: 75 μm / 3 mils

Figure 11. Recommended stencil window position in mm



3.3 Solder paste

1. Halide-free flux qualification ROL0 according to ANSI/J-STD-004.
2. "No clean" solder paste is recommended.
3. Offers a high tack force to resist component movement during high speed.
4. Use solder paste with fine particles: powder particle size 20-38 μm .

3.4 Placement

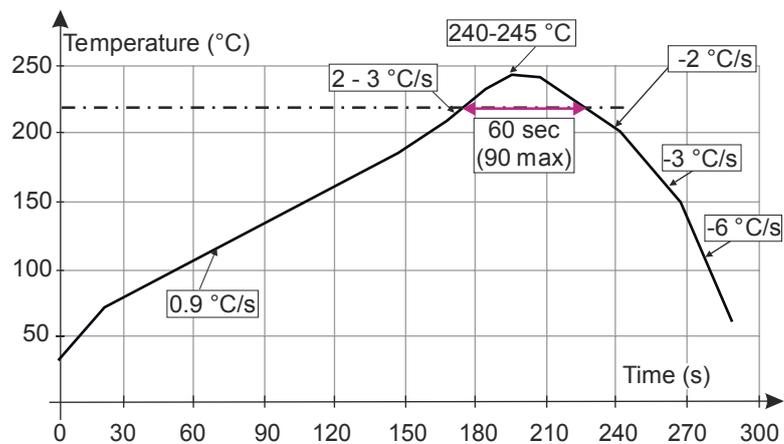
1. Manual positioning is not recommended.
2. It is recommended to use the lead recognition capabilities of the placement system, not the outline centering
3. Standard tolerance of ± 0.05 mm is recommended.
4. 1.0 N placement force is recommended. Too much placement force can lead to squeezed out solder paste and cause solder joints to short. Too low placement force can lead to insufficient contact between package and solder paste that could cause open solder joints or badly centered packages.
5. To improve the package placement accuracy, a bottom side optical control should be performed with a high resolution tool.
6. For assembly, a perfect supporting of the PCB (all the more on flexible PCB) is recommended during solder paste printing, pick and place and reflow soldering by using optimized tools.

3.5 PCB design preference

1. To control the solder paste amount, the closed via is recommended instead of open vias.
2. The position of tracks and open vias in the solder area should be well balanced. A symmetrical layout is recommended, to avoid any tilt phenomena caused by asymmetrical solder paste due to solder flow away.

3.6 Reflow profile

Figure 12. ST ECOPACK recommended soldering reflow profile for PCB mounting



Note: Minimize air convection currents in the reflow oven to avoid component movement. Maximum soldering profile corresponds to the latest IPC/JEDEC J-STD-020.

4 Ordering information

Figure 13.

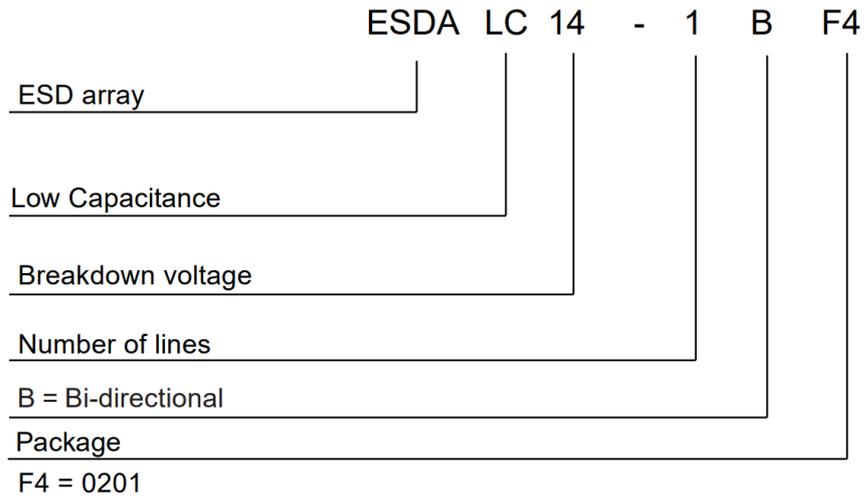


Table 4. Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
ESDALC14-1BF4	F ⁽¹⁾	ST0201	0.120 mg	15000	Tape and reel

1. The marking can be rotated by multiples of 90° to differentiate assembly location

Revision history

Table 5. Document revision history

Date	Version	Changes
11-Oct-2013	1	First issue.
03-Sep-2015	2	Updated Table 2.
14-Dec-2017	3	Updated weight from 0.116 mg to 0.120 mg.
05-Jul-2022	4	Updated Table 4 .

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